

# conga-XAF

## High graphics performance with low power consumption

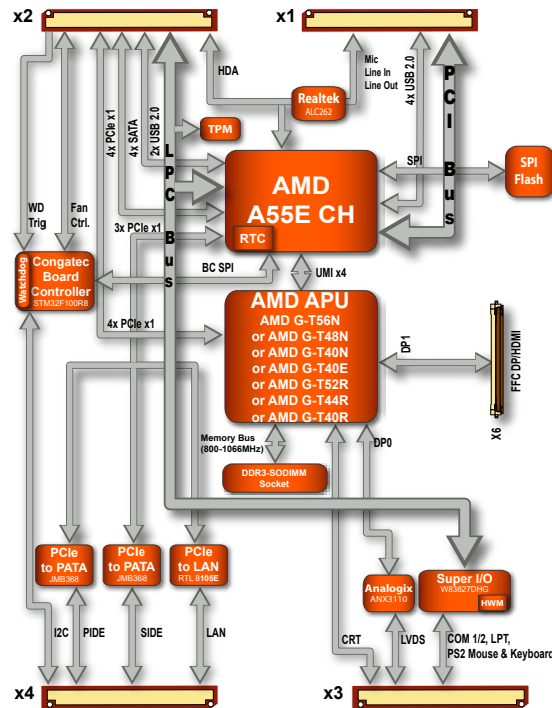


- Based on AMD Embedded G-Series Processors
- Best price/performance ratio
- High performance graphics



Formfactor	ETX® Spec 2.7. without ISA Support   XTX™ Extensions					
CPU	AMD Embedded G-Series Processors					
	AMD G-T56N	1.6 GHz	Dual Core	L1 cache 64KB	L2 cache 512kB x2	TDP 18 W
	AMD G-T52R	1.5 GHz	Single Core	L1 cache 64KB	L2 cache 512kB	TDP 18 W
	AMD G-T40R	1.0 GHz	Single Core	L1 cache 64KB	L2 cache 512kB	TDP 5.5 W
	AMD G-T40E	1.0 GHz	Dual Core	L1 cache 64KB	L2 cache 512kB x2	TDP 6.5 W
DRAM	Single channel up to one 4 GB DDR3 SO-DIMM memory (up to 1066 MHz)					
Chipset	AMD A55E Controller Hub					
Ethernet	10/100M Fast Ethernet   Realtek RTL8105E					
I/O Interfaces	4x PCI Express™ x1 lanes   4x Serial ATA®   2x EIDE (up to UDMA-66/100)   6x USB 2.0   PCI Bus (Rev. 2.3 compliant / 33 MHz)   2x Express Card LPC Bus   I²C (Fast Mode / 400 kHz Multi Maser)   Floppy   LPT   2x COM   PS/2					
Sound	High Definition Audio Interface and Analog MIC   Line In   Line Out by on-module HDA codec					
Graphics	Integrated High Performance Video   DirectX®11 graphics with UVD 3.0   Integrated VGA DAC   Dual Simultaneous Display Support   no PEG support					
LVDS	2x24 Bit   800x600 to 1920x1200@60Hz; VESA standard or JEDIA data mapping; Automatic Panel Detection via EDID/EPI					
DisplayPort	1x DisplayPort 1.1a shared with HDMI port   resolutions up to 2560x1600 - 18W APU   1920x1200 - 9W APU					
HDMI or DVI	1x HDMI 1.3 Port   shared with DisplayPort   resolutions up to 1920x1080 / 1920x1200 for DVI mode					
CRT	400 MHz RAMDAC   resolutions up to 2560x1600 - 18W APU   1920x1200 9W APU					
congatec Board Controller	Multi Stage Watchdog   non-volatile User Data Storage   Manufacturing and Board Information   Board Statistics   BIOS Setup Data   Backup I²C bus (fast mode / 400 kHz / multi-master)   Power Loss Control					
Embedded BIOS Features	AMI-Aptio UEFI BIOS with congatec Embedded BIOS features					
Security	The conga-XAF can be optionally equipped with a discrete "Trusted Platform Module" (TPM). It is capable of calculating efficient hash and RSA algorithms with key lengths up to 2,048 bits and includes a real random number generator. Security sensitive applications such as gaming and e-commerce will benefit also with improved authentication   integrity and confidence levels.					
Power Management	ACPI 3.0 with battery support					
Operating Systems	Microsoft® Windows8   Microsoft® Windows7   Microsoft® Windows XP   Microsoft® Windows® embedded Standard   Microsoft® Windows CE 6.0 Windows Embedded Compact 7   Linux					
Power Consumption	Typ. application: 9 .. 18 W.   see manual for full details   CMOS Battery Backup					
Temperature	Operating: 0 .. +60°C   Storage: -20 .. +80°C					
Humidity	Operating: 10 - 90% r. H. non cond.   Storage: 5 - 95% r. H. non cond.					
Size	95 x 114 mm (3.7" x 4.5")					

# conga-XAF | Block diagram



# conga-XAF | Order Information

Article	PN	Description
conga-XAF/T56N	041031	AMD G-Series dual core processor T56N 1.6GHz   1MB L2 cache and 1066MT/s DDR3 SODIMM memory interface for up to 4GB
conga-XAF/T40N	041033	AMD G-Series dual core processor T40N 1.0GHz   1MB L2 cache and 1066MT/s DDR3 SODIMM memory interface for up to 4GB
conga-XAF/T52R	041034	AMD G-Series single core processor T52R 1.5GHz   512kB L2 cache and 1066MT/s DDR3 SODIMM memory interface for up to 4GB
conga-XAF/T44R	041035	AMD G-Series single core processor T44R 1.2GHz   512kB L2 cache and 1066MT/s DDR3 SODIMM memory interface for up to 4GB
conga-XAF/T40R	041036	AMD G-Series single core processor T40R 1.0GHz   5.5W   1MB L2 cache and 1066MT/s DDR3 SODIMM memory interface for up to 4GB
conga-XAF/T40E	041037	AMD G-Series dual core processor T40E 1.0GHz   6.5W   1MB L2 cache and 1066MT/s DDR3 SODIMM memory interface for up to 4GB
conga-XAF/HSP-B	041050	Standard heatspreader for XTX module conga-XAF and EAF. All standoffs are with 2.7mm bore hole
conga-XAF/HSP-T	041051	Standard heatspreader for XTX module conga-XAF and EAF. All standoffs are M2.5mm thread
conga-XAF/CSP-B	041055	Standard passive cooling solution for modules conga-XAF and EAF. All standoffs are with 2.7mm bore hole
conga-XAF/CSP-T	041056	Standard passive cooling solution for modules conga-XAF and EAF. All standoffs are M2.5mm thread
conga-XAF/CSA-B	041057	Standard active cooling solution for modules conga-XAF and EAF. Integrated 12V fan. All standoffs are with 2.7mm bore hole
conga-XAF/CSA-T	041058	Standard active cooling solution for modules conga-XAF and EAF. Integrated 12V fan. All standoffs are M2.5mm thread
DDR3-SODIMM-1066 (1GB)	068750	DDR3 SODIMM memory module with 1066MT/s and 1GB RAM
DDR3L-SODIMM-1600 (2GB)	068755	DDR3L SODIMM memory module with 1600 MT/s (PC3L-12800S) and 2GB RAM
DDR3L-SODIMM-1600 (4GB)	068756	DDR3L SODIMM memory module with 1600 MT/s (PC3L-12800S) and 4GB RAM
<b>Accessories</b>		
conga-Xeval	019482	Evaluation carrier board for XTX-modules
conga-XDVI	098637	Evaluation platform to convert SDVO to DVI-D
conga-Xdebug	041784	XTX debugging platform. Including cable for COM   PS/2 and VGA
conga-FPA2	047250	Flatpanel prototype adapter to develop your own flatpanel adapter Including cables set
XTX/ETX-baseboard-socket-3	400006	Connector for ETX and XTX carrier boards   height 3.0 mm   packing unit 8 pieces
XTX/ETX-baseboard-socket-9.5	400009	Connector for ETX and XTX carrier boards   height 9.5 mm   packing unit 8 pieces
conga-LDVI/EPI	011115	LVDS to DVI adapter board for digital fl at panels with a graphics resolution up to 1280x1024 pixel

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- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

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